

ABSTRACT OF THE DISCLOSURE

A substrate and method of encapsulating a substrate based electronic package using injection molding and a two piece mold is described. The substrate has a barrier material formed on a gating region of the substrate. The barrier material can be formed directly over circuit wiring traces formed on the substrate thereby avoiding restrictions on the location of circuit wiring traces. The barrier material and encapsulant are chosen such that the adhesive force between the barrier material and the encapsulant is greater than the adhesive force between the barrier material and the substrate. When the mold runner is broken away the barrier material is also peeled away without damage to the substrate or circuit wiring traces.

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